

Please add claims 31-39 as follows:

- 31. (New) The apparatus of claim 30 wherein the coating comprises a uniform thickness.
- 32. (New) The apparatus of claim 30 wherein the coating conforms to the geometric configuration of the electronic device.
- 33. (New) The apparatus of claim 30 wherein the coating comprises a polymer.
- 34. (New) The apparatus of claim 33 wherein the polymer comprises poly-para-xylylene.
- 35. (New) The apparatus of claim 30 wherein the electronic device comprises an integrated power device (IPD).
- 36. (New) The apparatus of claim 30 wherein the electronic device further comprises a semiconductor.
- 37. (New) The apparatus of claim 30 wherein the electronic device further comprises a power semiconductor.
- 38. (New) The apparatus of claim 30 wherein the window restricts the region of the termination to which solder can adhere, the exposed portion defining a location for a solder bond.
- 39. (New) The apparatus of claim 30 wherein the electronic device comprises a plurality of conductive terminations and the conductive coating comprises a plurality of windows. --